

# UMX82B96

Preliminary

LINEAR INTEGRATED CIRCUIT

# I<sup>2</sup>C COMPATIBLE DUAL BIDIRECTIONAL BUS BUFFER

#### DESCRIPTION

The UTC **UMX82B96** is a bus buffer that supports bidirectional data transfer between an  $I^2C$  bus and a range of other bus configurations with different voltage and current levels.

One of the advantages of the UTC **UMX82B96** is that it supports longer cables/traces and allows for more devices per  $I^2C$  bus because it can isolate bus capacitance such that the total loading (devices and trace lengths) of the new bus or remote  $I^2C$  nodes are not apparent to other  $I^2C$  buses (or nodes). The restrictions on the number of  $I^2C$  devices in a system due to capacitance, or the physical separation between them, are greatly improved.

The device is able to provide galvanic isolation (optocoupling) or use balanced transmission lines (twisted pairs), because separate directional Tx and Rx signals are provided. The Tx and Rx signals may be connected directly (without causing bus latching), to provide an bidirectional signal line with I<sup>2</sup>C properties (open-drain driver). Likewise, the Ty and Ry signals may also be connected together to provide an bidirectional signal line with I<sup>2</sup>C properties (open-drain driver). This allows for a simple communication design, saving design time and costs.

#### FEATURES

- \* Operating Power-Supply Voltage Range of 2V to 15V
- \* Can Interface Between I<sup>2</sup>C Buses Operating at Different Logic Levels (2V to 15V)
- \* Outputs on the Transmission Side (Tx/Ty) Have High Current Sink Capability for Driving Low-Impedance or High-Capacitive Buses
- \* Interface With Optoelectrical Isolators and Similar Devices That Need Unidirectional Input and Output Signal Paths by Splitting I<sup>2</sup>C Bus Signals Into Pairs of Forward (Tx/Ty) and Reverse (Rx/Ry) Signals
- \* 400-kHz Fast I<sup>2</sup>C Bus Operation Over at Least 20 Meters of Wire



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#### **ORDERING INFORMATION**

Ordering	Number	Deskase	Decking
Lead Free	Halogen Free	Раскаде	Packing
UMX82B96L-S08-R	UMX82B96G-S08-R	SOP-8	Tape Reel



#### MARKING





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## ■ PIN CONFIGURATION



### PIN DESCRIPTION

PIN NO.	PIN NAME	DESCRIPTION
1	Sx	Serial data bus or SDA. Connect to $V_{CC}$ of I <sup>2</sup> C master through a pull up resistor.
2	Rx	Receive signal. Connect to V <sub>CC</sub> of UTC UMX82B96 through a pull up resistor.
3	Тх	Transmit signal. Connect to $V_{CC}$ of UTC <b>UMX82B96</b> through a pull up resistor.
4	GND	Ground
5	Ту	Transmit signal. Connect to $V_{CC}$ of UTC <b>UMX82B96</b> through a pull up resistor.
6	Ry	Receive signal. Connect to V <sub>CC</sub> of UTC UMX82B96 through a pull up resistor.
7	Sy	Serial clock bus or SCL. Connect to V <sub>CC</sub> of I <sup>2</sup> C master through a pull up resistor.
8	V <sub>cc</sub>	Supply voltage

#### BLOCK DIAGRAM





#### ■ ABSOLUTE MAXIMUM RATING (Unless otherwise specified.)

PARAM	ETER	SYMBOL	RATINGS	UNIT
Supply Voltage on V <sub>CC</sub> Pin		V <sub>cc</sub>	-0.3 ~ 18	V
Voltage on Duffered Input	Sx or Sy (SDA or SCL)	N/	-0.3 ~ 18	V
Voltage on Buffered Input	Rx or Ry	VI	-0.3 ~ 18	V
Voltage on Buffered Output	Sx or Sy (SDA or SCL)	N/	-0.3 ~ 18	V
	Tx or Ty	Vo	-0.3 ~ 18	V
	Sx or Sy		250	mA
Continuous Output Current	Tx or Ty	IO	250	mA
Continuous Current through V <sub>CC</sub> or GND		Icc	250	mA
Operating Free-Air Temperature		T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +165	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

#### RECOMMENDED OPERATING CONDITIONS

				UNIT			
PARAMETER			STMBOL	MIN	TYP	MAX	
Supply Voltage			Vcc	2		15	V
Low-Level Output Current	Sx, Sy	V <sub>Sx</sub> , V <sub>Sy</sub> =1V, V <sub>Rx</sub> , V <sub>Ry</sub> ≤ 0.42V				3	mA
	Tx, Ty V <sub>Sx</sub> , V <sub>Tx</sub> ,		4V, <sup>IOL</sup> 4V			30	mA
Maximum	Sx, Sy	V <sub>Tx</sub> , V <sub>Ty</sub> =0.4V				15	V
Input/Output Voltage Level	Тх, Ту	V <sub>Sx</sub> , V <sub>Sy</sub> =0.4V	V <sub>IOmax</sub>			15	V
Low-Level Input Voltage Difference	Sx, Sy		VILdiff			0.4	V

#### THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	$\theta_{JA}$	120	°C/W



## ELECTRICAL CHARACTERISTICS

(V<sub>CC</sub> = 2.3V ~ 5.5V, 15V, voltages are specified with respect to GND, unless otherwise specified)

					-	T <sub>A</sub> =25°	Ċ	T <sub>A</sub> =-40~+85°C			
PARAMETI	ER	SYMBOL	TEST CO	ONDITIONS	MIN	TYP (Note 1)	MAX	MIN	TYP	MAX	UNIT
Temperature Coefficient of Input Thresholds	Sx, Sy	$\Delta V / \Delta T_{IN}$				-2			-2		mV/°C
Low-Level	Sx Sv	Voi	I <sub>Sx</sub> , I <sub>Sγ</sub> =3mA		0.75	0.88	1	0.6		1.1	V
Output Voltage	ол, су	VOL	I <sub>Sx</sub> , I <sub>Sγ</sub> =0.2mA		0.6	0.73	0.8	0.5		0.9	V
Temperature Coefficient of Output Low Levels (Note 2)	Sx, Sy	ΔV/ΔΤ <sub>ΟυΤ</sub>	I <sub>Sx</sub> , I <sub>Sy</sub> =0.2mA			-1.8			-1.8		mV/°C
Quiescent Supply	Current	I <sub>cc</sub>	Sx=Sy=V <sub>CC</sub>			0.9	1.8			2	mA
Additional Supply Current Per Pin Low	Тх, Ту	ΔI <sub>CC</sub>				1.7	2.75			3	mA
			V <sub>Sx</sub> , V <sub>Sy</sub> >2V, V	<sub>Rx</sub> , V <sub>Ry</sub> =Low	7	20		5.5			mA
Dynamic Output Sink Capability			V <sub>Sx</sub> , V <sub>Sy</sub> =2.5V V <sub>Rx</sub> , V <sub>Ry</sub> =High	V <sub>CC</sub> =2.3V~2.7V		0.1	1			1	μA
on I <sup>2</sup> C Bus	Sx, Sy	I <sub>IOS</sub>	V <sub>Sx</sub> , V <sub>Sy</sub> =5V	V <sub>CC</sub> =3V~3.6V		0.1	1			1	μA
Leakage Current			V <sub>Rx</sub> , V <sub>Ry</sub> =High	V <sub>CC</sub> =4.5V~5.5V		0.1	1			1	μA
on I <sup>2</sup> C Bus			V <sub>Sx</sub> , V <sub>Sy</sub> =15V V <sub>Rx</sub> , V <sub>Ry</sub> =High	V <sub>CC</sub> =15V		0.1	1			1	μA
Dynamic Output Sink Capability on Buffered Bus			$V_{Tx}$ , $V_{Ty}$ >1V, $V_{Sx}$ , $V_{Sy}$ =Low C I <sup>2</sup> Cbus=0.4V	Dn	60	80		60			mA
	Тх, Ту	I <sub>IOT</sub>	V <sub>Tx</sub> , V <sub>Ty</sub> =V <sub>CC</sub> =2.5V, V <sub>Sx</sub> , V <sub>Sy</sub> =High	V <sub>CC</sub> =2.3V~2.7V		0.1	1			1	μA
Leakage Current			V <sub>Tx</sub> , V <sub>Ty</sub> =V <sub>CC</sub> =3.3V, V <sub>Sx</sub> , V <sub>Sy</sub> =High	V <sub>CC</sub> =3V~3.6V		0.1	1			1	μA
on Buffered Bus			V <sub>Tx</sub> , V <sub>Ty</sub> =V <sub>CC</sub> =5V, V <sub>Sx</sub> , V <sub>Sy</sub> =High	V <sub>CC</sub> =4.5V~5.5V		0.1	1			1	μA
			V <sub>Tx</sub> , V <sub>Ty</sub> =V <sub>CC</sub> =15V, V <sub>Sx</sub> , V <sub>Sy</sub> =High	V <sub>CC</sub> =15V		0.1	1			1	μA
Input Current from I <sup>2</sup> C Bus	Sx, Sy	_	Bus Low, V <sub>Rx</sub> , '	V <sub>Ry</sub> =High		-1				1	μA
Input Current from Buffered Bus		h	Bus Low, V <sub>Rx</sub> , '	V <sub>Ry</sub> =0.4V		-1				1	μA
Leakage Current on Buffered Bus Input	кх, ку		V <sub>Rx</sub> , V <sub>Ry</sub> =V <sub>CC</sub>			-1				1.5	μA



UMX82B96

### LINEAR INTEGRATED CIRCUIT

#### ■ ELECTRICAL CHARACTERISTICS (Cont.)

(V<sub>CC</sub> = 2.3V ~ 5.5V, 15V, voltages are specified with respect to GND, unless otherwise specified)

				T <sub>A</sub> =25°C		T <sub>A</sub> =-40~+85°C				
PARAMET	PARAMETER SYME		TEST CONDITIONS		TYP (Note 1)	MAX	MIN	TYP	MAX	UNIT
S Input Threshold	Sx, Sy		Input Logic Level High Threshold (Note 3) on Normal I <sup>2</sup> C Bus		0.65	0.85			0.9	V
			Input Logic Level Low Threshold (Note 3) on Normal I <sup>2</sup> C Bus	0.6	0.65		0.3			V
		VIT	Input Logic Level High	0.58× V <sub>CC</sub>			0.58× V <sub>CC</sub>			V
	Rx, Ry		Input Threshold		0.5× V <sub>CC</sub>					V
			Input Logic Level Low			0.42× V <sub>CC</sub>			0.42× V <sub>CC</sub>	V
Input/Output Logic Level Difference (Note 4)	Sx, Sy	V <sub>IOdiff</sub>	(V <sub>Sx</sub> Output Low at 3mA) – (V <sub>Sx</sub> Input High Max) for I <sup>2</sup> C Applications	100	150		100			mV
V <sub>CC</sub> Voltage at which all Buses are Released	Sx, Sy Tx, Ty	V <sub>IOrel</sub>	Sx, Sy are Low, V <sub>CC</sub> Ramping, Voltage on Tx, Ty Lowered until Released	1			1			v
Temperature Coe of Release Voltag	efficient ge	$\Delta V / \Delta T_{REL}$			-4			-4		mV/°C
Input Capacitance	Rx, Ry	C <sub>IN</sub>			2.5	4			4	pF

Notes: 1. Typical value is at  $V_{CC}$  = 2.5V,  $T_A$  =25°C.

2. The output logic low depends on the sink current.

3. The input logic threshold is independent of the supply voltage.

4. The minimum value requirement for pullup current, 200µA, ensures that the minimum value for V<sub>SX</sub> output low always exceeds the minimum V<sub>Sx</sub> input high level to eliminate any possibility of latching. The specified difference is specified by design within any device. While the tolerances on absolute levels allow a small probability that the low from one Sx output is recognized by an Sx input of another. UTC UMX82B96, this has no consequences for normal applications.

#### ■ SWITCHING CHARACTERISTICS

(V<sub>CC</sub> = 5V, T<sub>A</sub> =25°C, no capacitive loads, voltages are specified with respect to GND, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Buffer Delay Time On Falling Input for Input $V_{Sx}$ (or $V_{Sy}$ ) = Input Switching Threshold to Output $V_{Tx}$ (or $V_{Ty}$ ) Output Falling 50% of $V_{LOAD}$ (Note 1)	t <sub>pzl</sub>	R <sub>Tx</sub> Pullup = 160Ω, C <sub>Tx</sub> = 7pF + Board Trace Capacitance		90		ns
Buffer Delay Time On Rising Input for Input $V_{Sx}$ (or $V_{Sy}$ ) = Input Switching Threshold to Output $V_{Tx}$ (or $V_{Ty}$ ) Output Reaching 50% of $V_{LOAD}$ (Note 2)	t <sub>plz</sub>	R <sub>Tx</sub> Pullup = 160Ω, C <sub>Tx</sub> = 7pF + Board Trace Capacitance		30		ns
Buffer Delay Time On Falling Input for Input $V_{Rx}$ (or $V_{Ry}$ ) = Input Switching Threshold to Output $V_{Sx}$ (or $V_{Sy}$ ) Output Falling 50% of $V_{LOAD}$ (Note 3)	t <sub>pzl</sub>	$R_{Sx}$ Pullup = 1500 $\Omega$ , $C_{Tx}$ = 7pF + Board Trace Capacitance		150		ns
Buffer Delay Time On Rising Input for Input $V_{Rx}$ (or $V_{Ry}$ ) = Input Switching Threshold to Output $V_{Sx}$ (or $V_{Sy}$ ) Output Reaching 50% of $V_{LOAD}$ (Note 4)	t <sub>plz</sub>	R <sub>Sx</sub> Pullup = 1500Ω, C <sub>Tx</sub> = 7pF + Board Trace Capacitance		150		ns

Notes: 1. The fall time of  $V_{Tx}$  from 5V to 2.5V in the test is approximately 15ns.

2. The rise time of  $V_{\text{Tx}}$  from 0V to 2.5V in the test is approximately 20ns.

3. The fall time of  $V_{\text{Sx}}$  from 5V to 2.5V in the test is approximately 50ns.

4. The rise time of  $V_{\text{Sx}}$  from 0.9V to 2.5V in the test is approximately 70ns.



#### TYPICAL APPLICATION CIRCUIT



Fig. 1 Interfacing an I<sup>2</sup>C Type of Bus With Different Logic Levels



Fig. 2 Galvanic Isolation of I<sup>2</sup>C-Bus Nodes via Opto-Couplers



## TYPICAL APPLICATION CIRCUIT (Cont.)



Fig. 3 Long-Distance I<sup>2</sup>C-Bus Communications

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